TITLE: METHOD AND APPARATUS FOR TRANSFER MOLDING ENCAPSULATION OF A SEMICONDUCTOR... Inventor: Richard W. Wensel Docket No.: 3061.6US

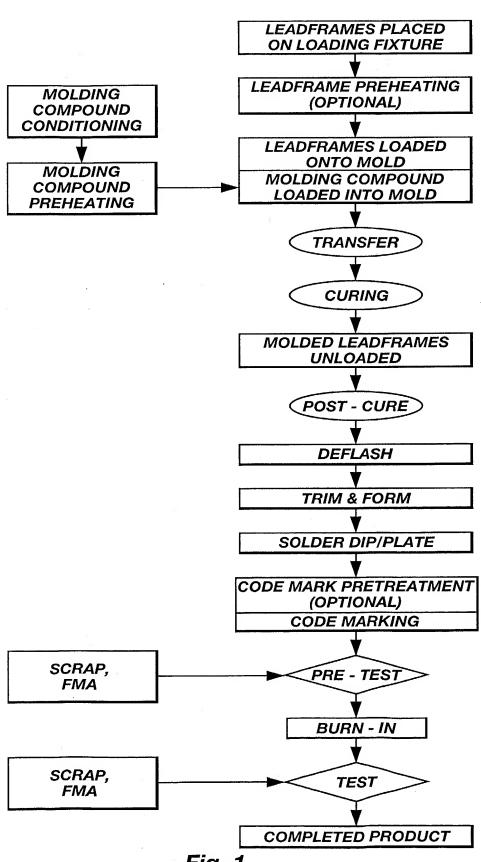
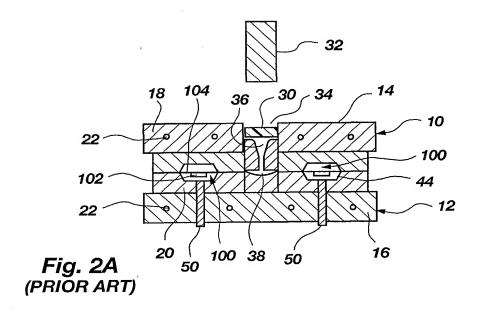


Fig. 1 (PRIOR ART)

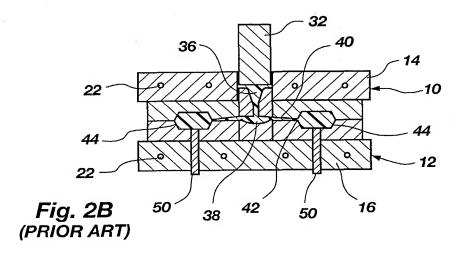
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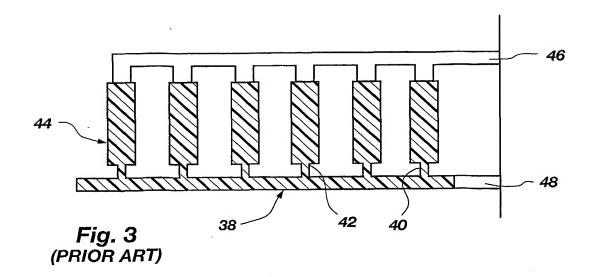


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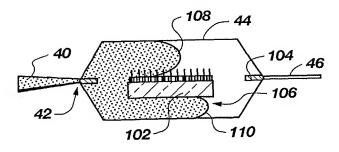


Fig. 4A (PRIOR ART)

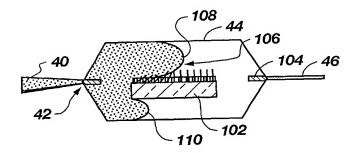


Fig. 4B (PRIOR ART)

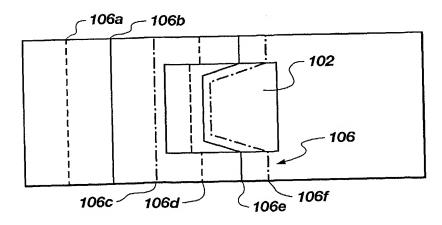


Fig. 4C (PRIOR ART)

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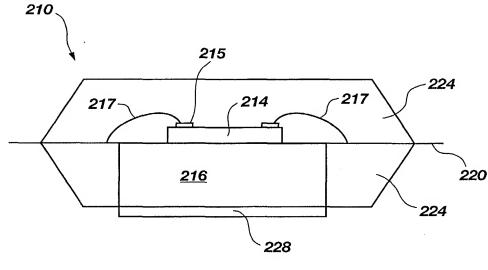


Fig. 5

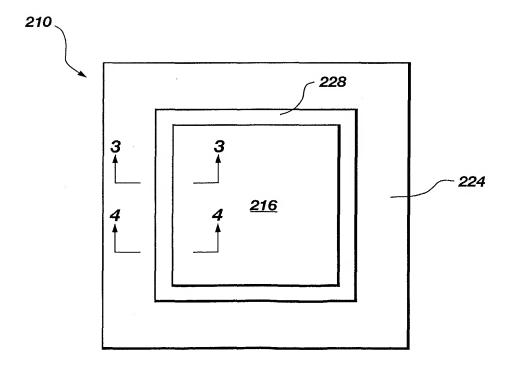


Fig. 6

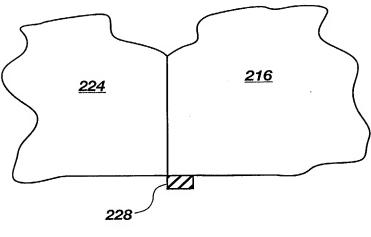


Fig. 7

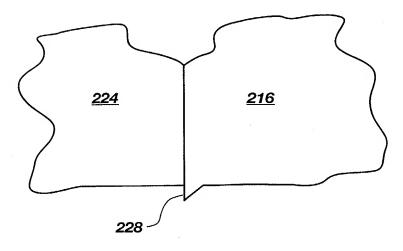


Fig. 8

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Inventor: Richard W. Wensel Docket No.: 3061.6US

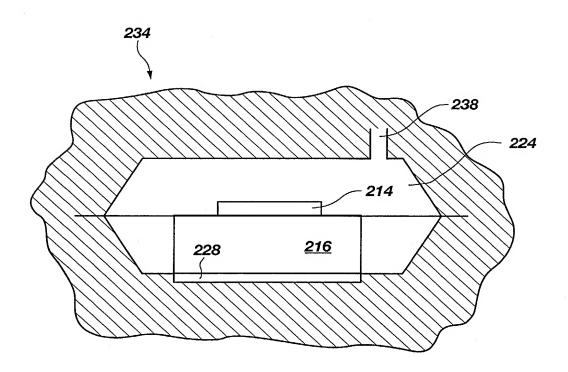


Fig. 9